

This Sheet Has Been Replaced



METHOD OF WORKING AN ORGANIC FILM

ABSTRACT

An organic film working method is provided which can permit an organic film to be worked at low costs through only a laser irradiation process, without resort to a wet process. Minute holes are formed in an organic film substrate by irradiating a first pulse laser beam (1) having a pulse width in the range between $10\mu\text{s}$ and 20ms so that any one of reactions of thermally decomposing an insulating film through the influence of heating action by irradiation of the laser beam and of generating a gas due to thermal decomposition may be caused and by irradiating a short pulse beam (5) having an irradiation beam spot size which expands to a range of extent of the thermally decomposed substance and having a pulse width of 200ns or less.

Fig. 1.